

INNOVATION PUT TO THE TEST



FORMFACTOR
Advanced Wafer Probe Solutions

FormFactor Inc. Overview

2010 Small / Mid Cap Conference

Tom St. Dennis, CEO

11/17/2010

Disclosure

FORWARD-LOOKING STATEMENTS: This presentation contains forward-looking statements within the meaning of the federal securities laws, including statements regarding business momentum, demand for our products and future growth. These forward-looking statements are based on current information and expectations that are inherently subject to change and involve a number of risks and uncertainties. Actual events or results might differ materially from those in any forward-looking statement due to various factors, including, but not limited to: changes in the market environment, including the demand for DRAM and Flash memory devices and certain other semiconductor devices and the status and momentum of transitions to DDRIII and to smaller technology nodes; the company's ability to implement on a timely and efficient basis a cost reduction plan, including reductions in workforce and discontinuing of manufacturing activities in Korea, the company's ability to ramp its manufacturing activities and transition certain manufacturing activities to Singapore on an efficient and timely basis, the company's ability to improve operating efficiency and return to profitability, and to timely deliver new products that meet its customer's testing requirements and lower their overall cost of test. Additional information concerning factors that could cause actual events or results to differ materially from those in any forward-looking statement is contained in the company's Form 10-K for the fiscal year ended December 26, 2009, as filed with the Securities and Exchange Commission ("SEC"), and subsequent SEC filings. Copies of the company's SEC filings are available at <http://investors.formfactor.com/edgar.cfm>. We assume no obligation to update the information in this presentation, to revise any forward-looking statements or to update the reasons actual results could differ materially from those anticipated in forward-looking statements.

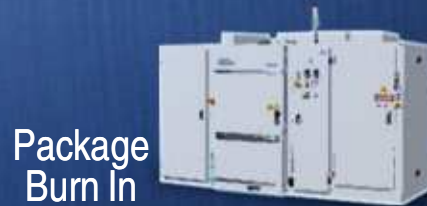
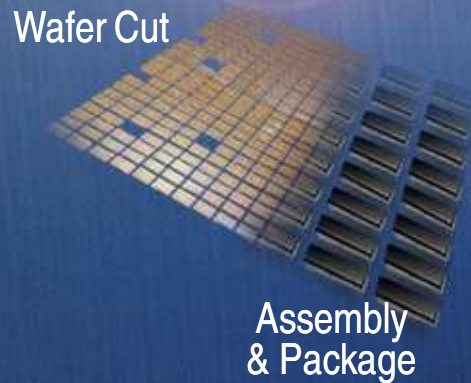
NON-GAAP MEASURES: This presentation includes GAAP and non-GAAP financial information. FormFactor excluded from one or more of the non-GAAP measures certain items as described, such as stock-based compensation expenses, and restructuring and impairment charges. By publishing the non-GAAP measures, the company's management intends to provide investors with additional information to further analyze the company's performance, core results and underlying trends. FormFactor's management evaluates results and makes operating decisions using both GAAP and non-GAAP measures. Non-GAAP results are not prepared in accordance with GAAP, and non-GAAP information should be considered a supplement to, and not a substitute for, financial statements prepared in accordance with GAAP. A reconciliation of our GAAP and non-GAAP measures can be found on our website.

Semiconductor Manufacturing

FRONT END



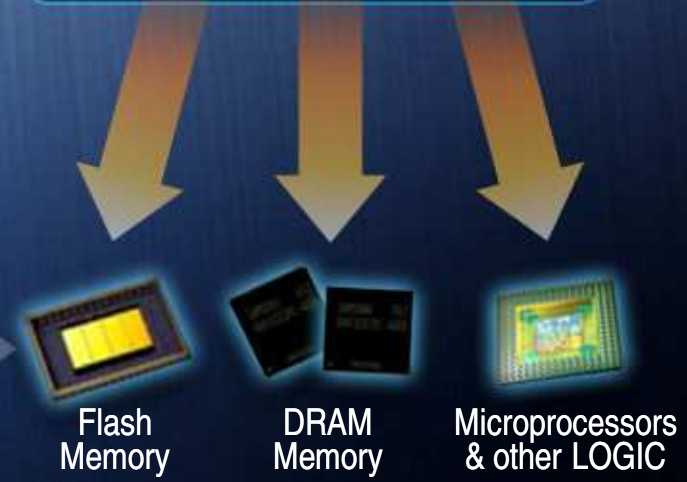
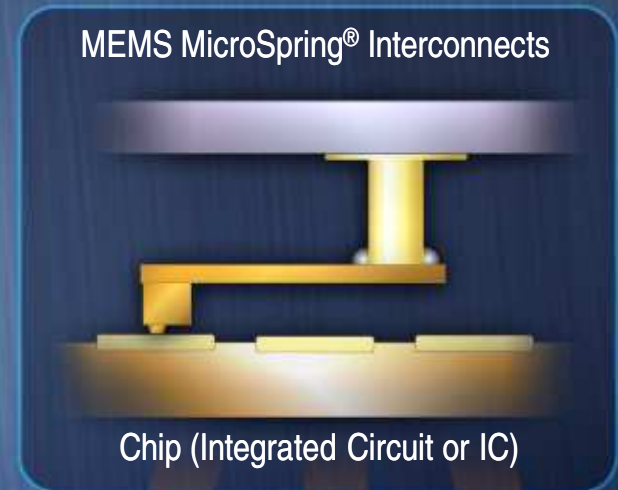
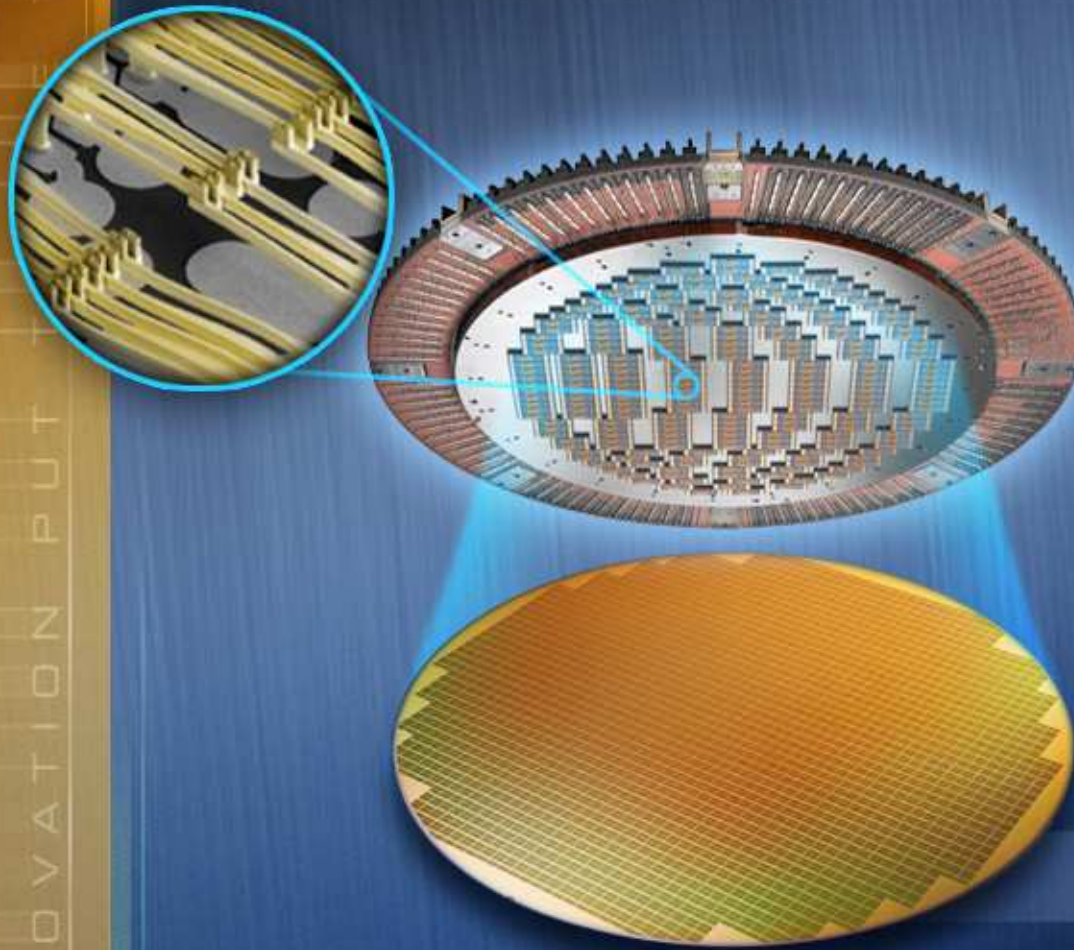
BACK END



INNOVATION PUTS THE TEST

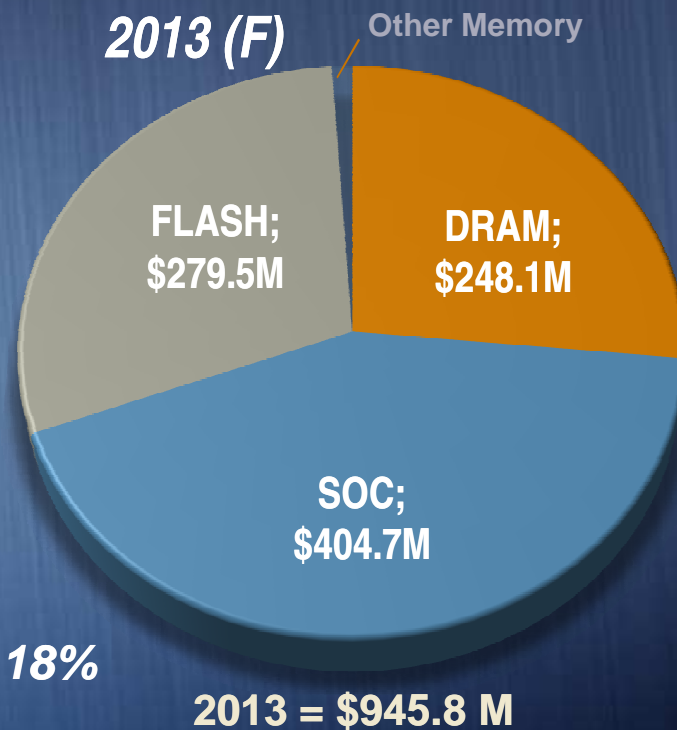
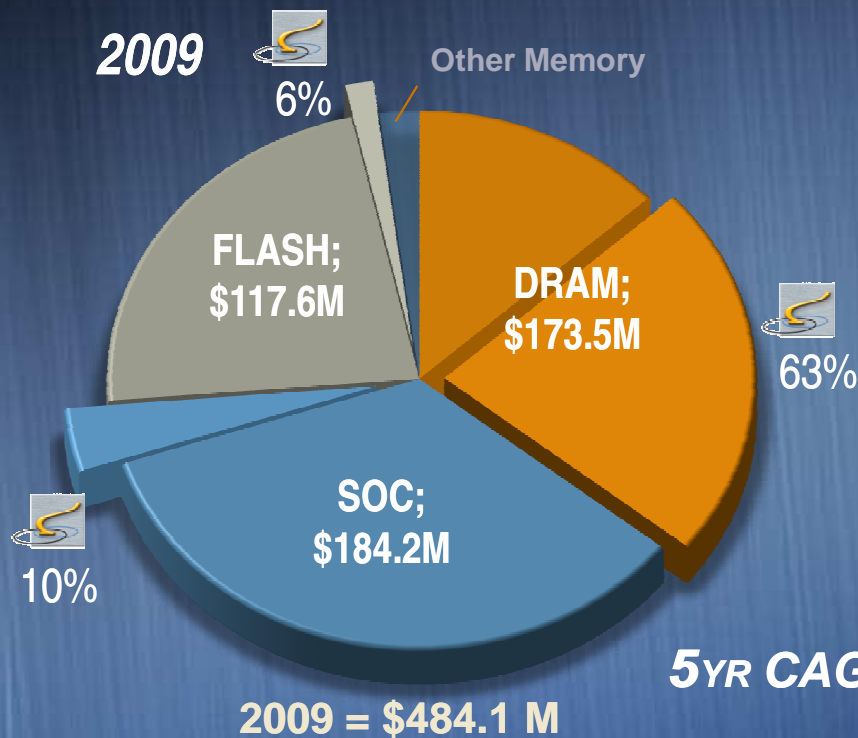
Advanced Wafer Probe Cards

Probe cards electrically test chips while they are still on the silicon wafer



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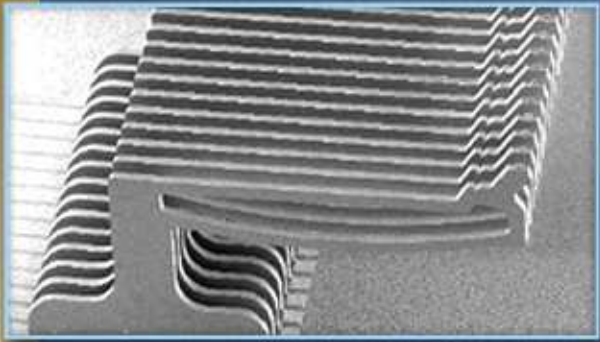
Advanced Probe Card Market Growth



Source: VLSI

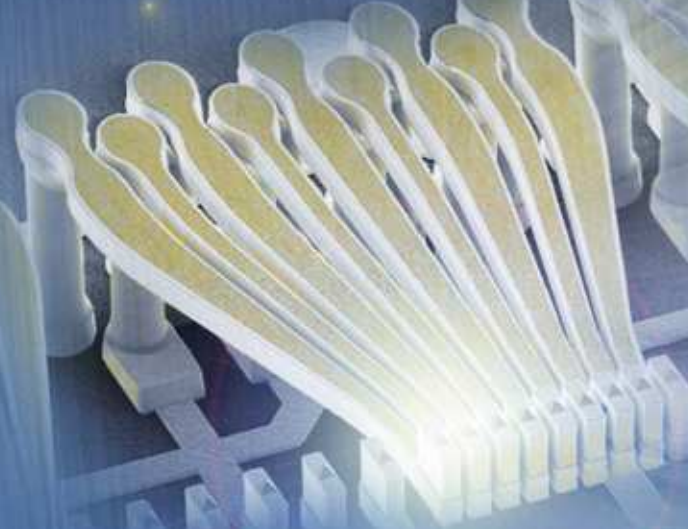
Technology Leadership

Competitive 2D MEMS PC



Contacts individually
assembled

FORM 3D MEMS PC



Lithographic processes for
fabrication and automated
assembly to improve accuracy
and manufacturability

Scales to smaller sizes with
superior electromechanical
properties

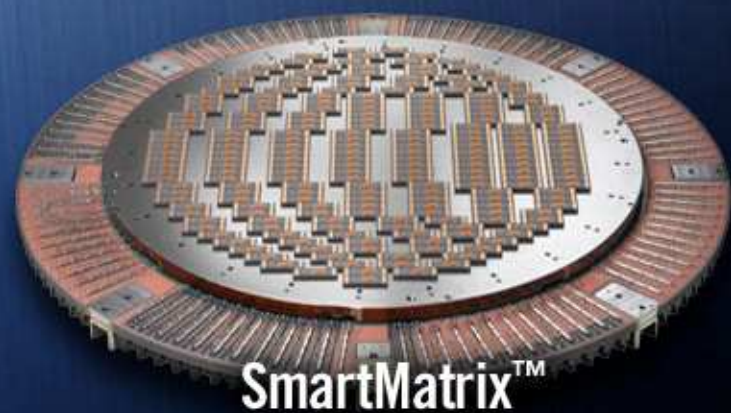


Advanced Probe Card vs. Cantilever Solutions

- Best XY control → Smaller Pads, More die per wafer (DPW)
- Best Z control → Better Yield
- Zero Soak Time → Better Tester Utilization
- Signal Integrity → Fewer “False Negative”, Better Yield
- High Parallelism → Tester Throughput, Lower Cost of Test
- Excellent CRES → Better Yield
- Less Cleaning / Less Maintenance → Better Tester Utilization



TouchMatrix™



SmartMatrix™

Framework for Recovery

Q4 '10 – Q1 '11	Q2 '11 - Q4 '11	FY12 and beyond
<u>Stabilize</u>	<u>Compete</u>	<u>Lead</u>
<u>Customers</u> <ul style="list-style-type: none"> • OTD – Meet Commitments 	<u>Customers</u> <ul style="list-style-type: none"> • Lead time improvements 	<u>Customers</u> <ul style="list-style-type: none"> • Logic / SOC • Foundry / Fabless
<u>Products & Technology</u> <ul style="list-style-type: none"> • SmartMatrix™ • TouchMatrix™ 	<u>Products & Technology</u> <ul style="list-style-type: none"> • 2nd Generation of Matrix Architecture for DRAM and Flash Markets 	<u>Products & Technology</u> <ul style="list-style-type: none"> • TSV solution • Advanced Spring Technologies for SOC
<u>Operational Performance</u> <ul style="list-style-type: none"> • \$0 cash burn @ \$50M / qtr 	<u>Operational Performance</u> <ul style="list-style-type: none"> • Non-GAAP profit @ 65M / qtr 	<u>Operational Performance</u> <ul style="list-style-type: none"> • 20% Operating Margin

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Investor Presentation

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